

74F138

1-of-8 Decoder/Demultiplexer

General Description

The F138 is a high-speed 1-of-8 decoder/demultiplexer. This device is ideally suited for high-speed bipolar memory chip select address decoding. The multiple input enables allow parallel expansion to a 1-of-24 decoder using just three F138 devices or a 1-of-32 decoder using four F138 devices and one inverter.

Features

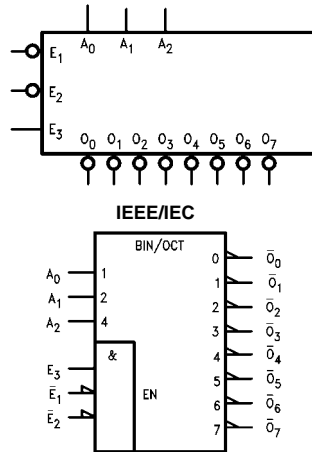
- Demultiplexing capability
- Multiple input enable for easy expansion
- Active LOW mutually exclusive outputs

Ordering Code:

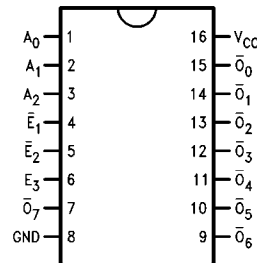
Order Number	Package Number	Package Description
74F138SC	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
74F138SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F138PC	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbols



Connection Diagram



Unit Loading/Fan Out

Pin Names	Description	U.L.	Input I_{IH}/I_{IL}
		HIGH/LOW	Output I_{OH}/I_{OL}
A_0 - A_2	Address Inputs	1.0/1.0	20 μ A/-0.6 mA
\bar{E}_1, \bar{E}_2	Enable Inputs (Active LOW)	1.0/1.0	20 μ A/-0.6 mA
E_3	Enable Input (Active HIGH)	1.0/1.0	20 μ A/-0.6 mA
\bar{O}_0 - \bar{O}_7	Outputs (Active LOW)	50/33.3	-

Truth Table

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

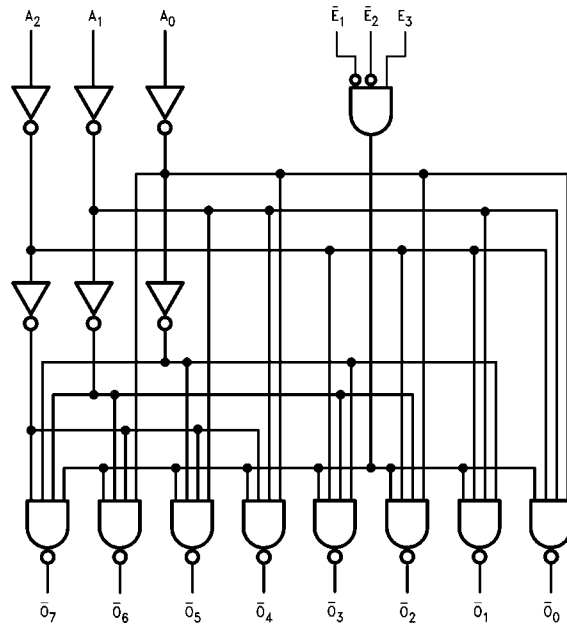
Functional Description

The F138 high-speed 1-of-8 decoder/demultiplexer accepts three binary weighted inputs (A_0, A_1, A_2) and, when enabled, provides eight mutually exclusive active LOW outputs (\bar{O}_0 - \bar{O}_7). The F138 features three Enable inputs, two active LOW (\bar{E}_1, \bar{E}_2) and one active HIGH (E_3). All outputs will be HIGH unless \bar{E}_1 and \bar{E}_2 are LOW and E_3 is HIGH. This multiple enable function allows easy parallel

expansion of the device to a 1-of-32 (5 lines to 32 lines) decoder with just four F138 devices and one inverter (See Figure 1). The F138 can be used as an 8-output demultiplexer by using one of the active LOW Enable inputs as the data input and the other Enable inputs as strobes. The Enable inputs which are not used must be permanently tied to their appropriate active HIGH or active LOW state.

FIGURE 1. Expansion to 1-of-32 Decoding

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V _{CC} = 0V)	
Standard Output	-0.5V to V _{CC}
3-STATE Output	-0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I _{OL} (mA)
ESD Last Passing Voltage (Min)	4000V

Recommended Operating Conditions

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

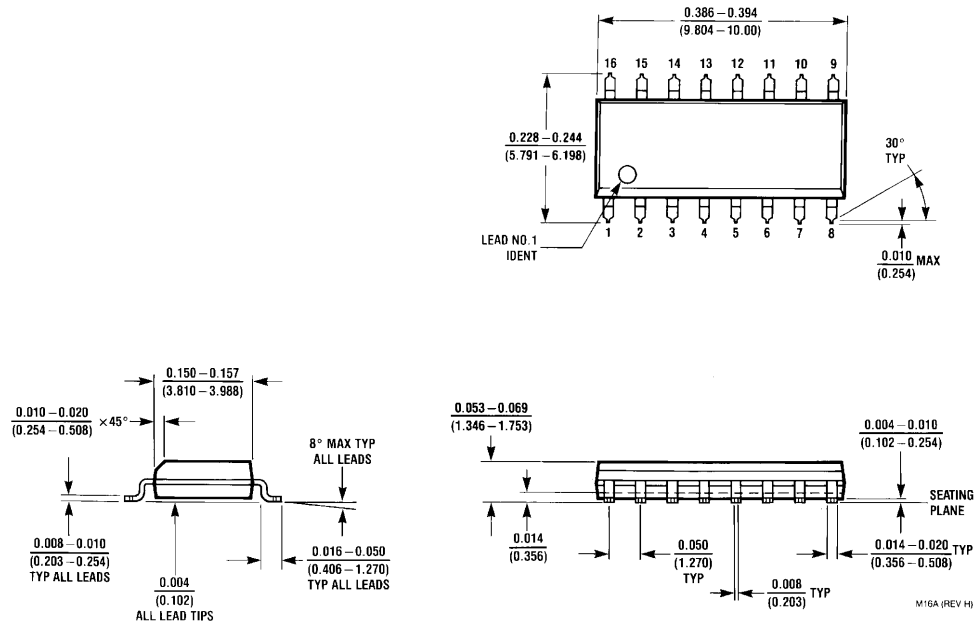
DC Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage			-1.2	V	Min	I _{IN} = -18 mA
V _{OH}	Output HIGH Voltage	10% V _{CC} 5% V _{CC}	2.5 2.7		V	Min	I _{OH} = -1 mA I _{OH} = -1 mA
V _{OL}	Output LOW Voltage	10% V _{CC}		0.5	V	Min	I _{OL} = 20 mA
I _{IH}	Input HIGH Current			5.0	μA	Max	V _{IN} = 2.7V
I _{BVI}	Input HIGH Current Breakdown Test			7.0	μA	Max	V _{IN} = 7.0V
I _{CEX}	Output HIGH Leakage Current			50	μA	Max	V _{OUT} = V _{CC}
V _{ID}	Input Leakage Test	4.75			V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current			3.75	μA	0.0	V _{IOD} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current			-0.6	mA	Max	V _{IN} = 0.5V
I _{OS}	Output Short-Circuit Current	-60		-150	mA	Max	V _{OUT} = 0V
I _{CCH}	Power Supply Current		13	20	mA	Max	V _O = HIGH
I _{CCL}	Power Supply Current		13	20	mA	Max	V _O = LOW

AC Electrical Characteristics

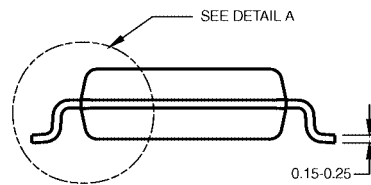
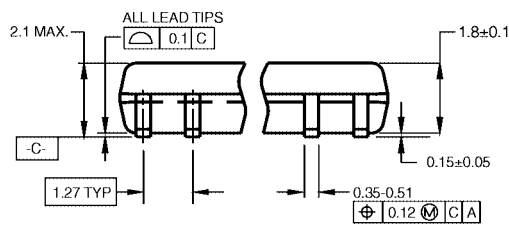
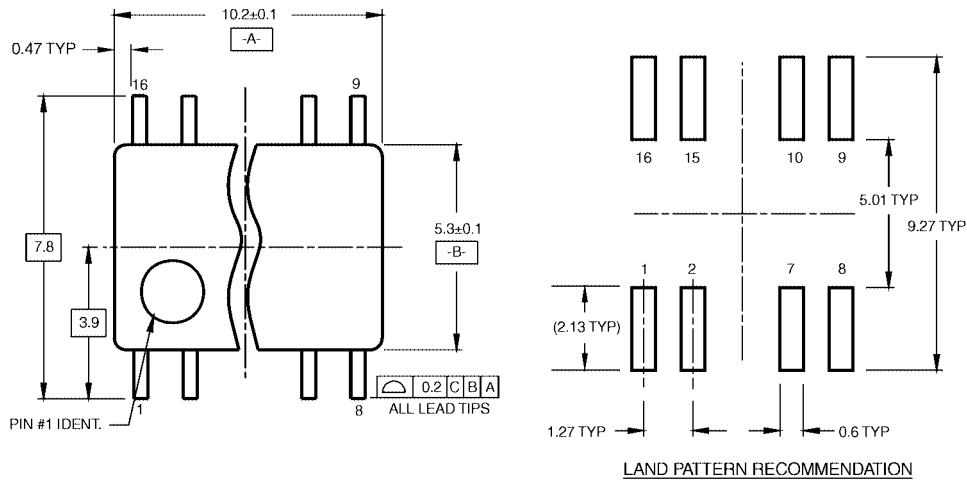
Symbol	Parameter	T _A = +25°C V _{CC} = +5.0V C _L = 50 pF			T _A = 0°C to +70°C V _{CC} = +5.0V C _L = 50 pF		Units
		Min	Typ	Max	Min	Max	
t _{PLH}	Propagation Delay A _n to \bar{O}_n	3.5	5.6	7.5	3.5	8.5	ns
t _{PHL}		4.0	6.1	8.0	4.0	9.0	
t _{PLH}	Propagation Delay \bar{E}_1 or \bar{E}_2 to \bar{O}_n	3.5	5.4	7.0	3.5	8.0	ns
t _{PHL}		3.0	5.3	7.0	3.0	7.5	
t _{PLH}	Propagation Delay E ₃ to \bar{O}_n	4.0	6.2	8.0	4.0	9.0	ns
t _{PHL}		3.5	5.6	7.5	3.5	8.5	

Physical Dimensions inches (millimeters) unless otherwise noted



16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow Package Number M16A

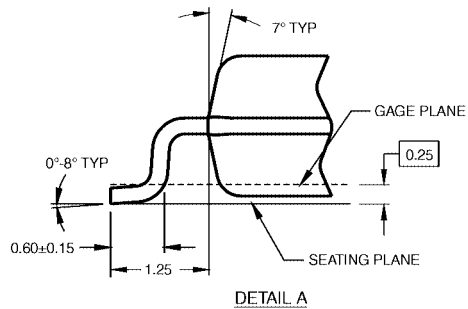
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

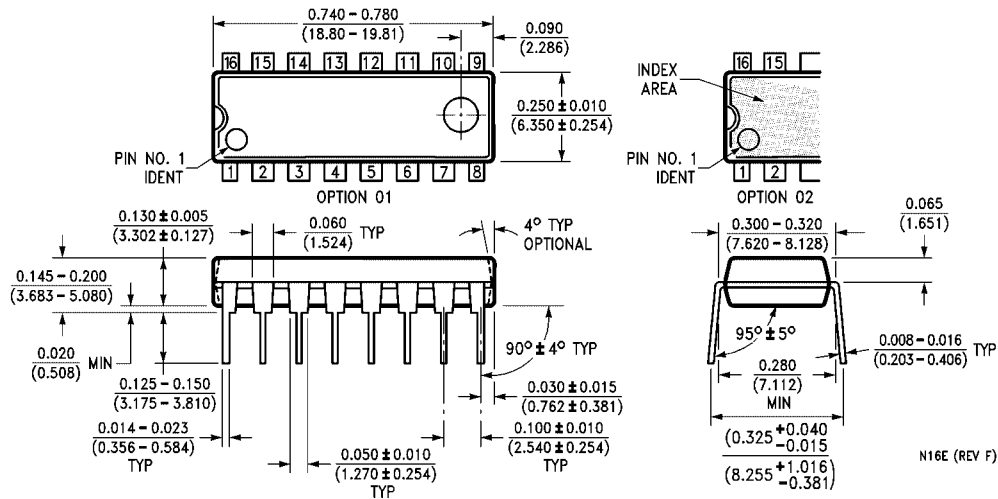
- NOTES:
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M16DRevB1



16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M16D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N16E

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